

描述 / Descriptions

表面贴装整流二极管，反向电压：50V~1000V，正向电流：3.0A，SMB 封装。
Surface Mount General Purpose Silicon Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:3.0A ,SMB package.

特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。
Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

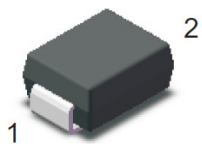
用途 / Applications

一般用途。
General purpose.

内部等效电路 / Equivalent Circuit

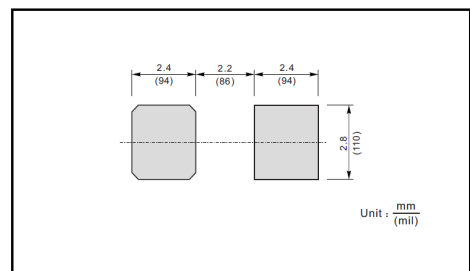


引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



印章代码 / Marking

见印章说明。 See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	90							A
Typical Junction Capacitance at VR=4V f=1MHz	C_j	35							pF
Typical Thermal Resistance ¹⁾	$R_{\theta JA}$	48							°C/W
	$R_{\theta JC}$	16							
Operating and Storage Temperature Range	T_j, T_{stg}	-55~+150							°C

Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X 5cm) copper pad areas.

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	
Maximum Instantaneous Forward Voltage	V_F	$I_F=3.0A$	1.1							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	I_R	$T_a=25^\circ C$	5.0							μA
		$T_a=125^\circ C$	100							μA

电参数曲线图 / Electrical Characteristic Curve

Fig.1 Forward Current Derating Curve

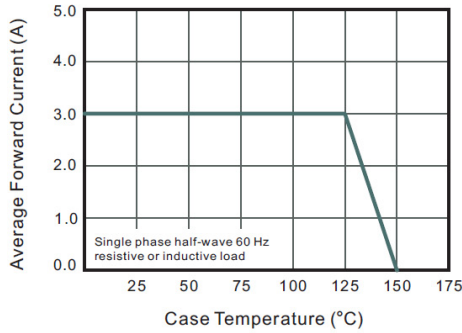


Fig.2 Typical Instaneous Reverse Characteristics

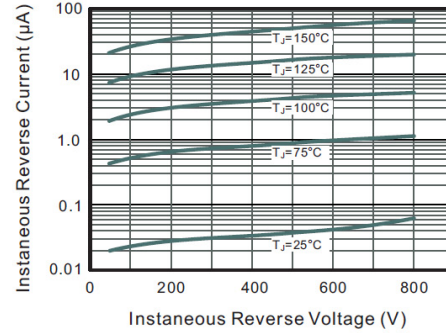


Fig.3 Typical Forward Characteristic

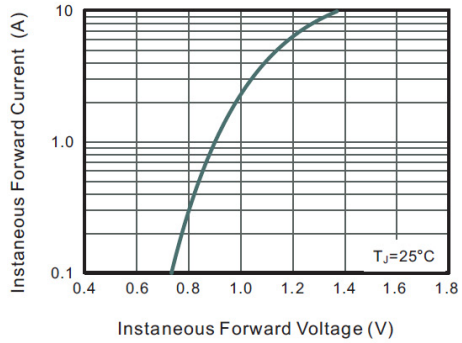


Fig.4 Typical Junction Capacitance

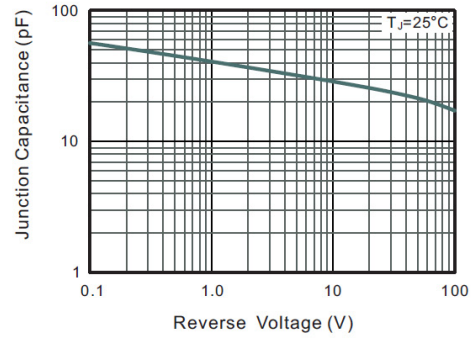
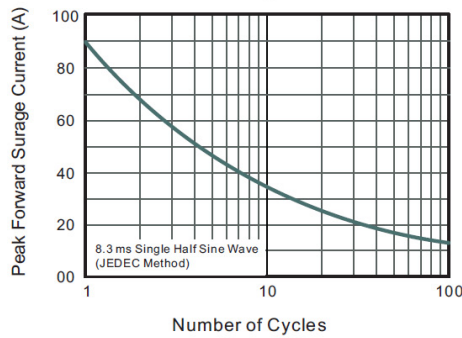
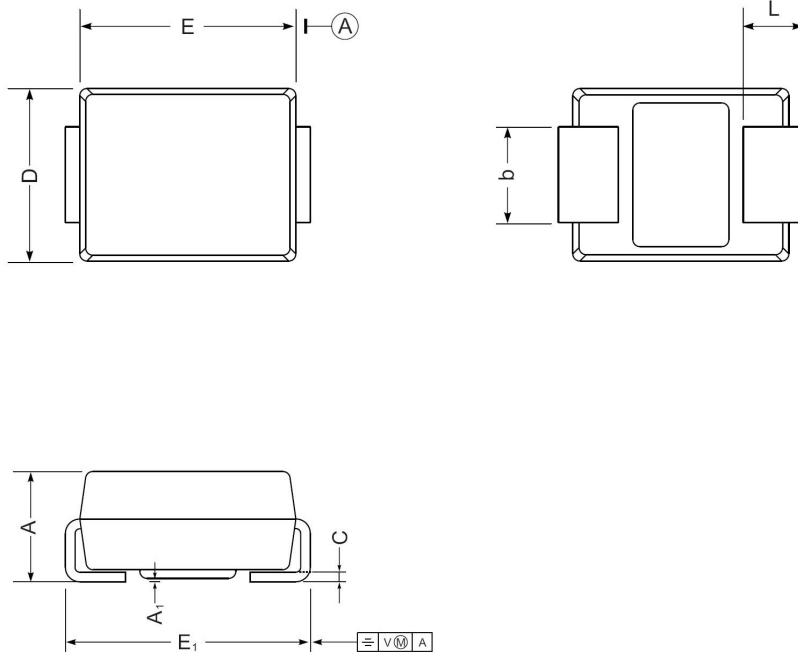


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



外形尺寸图 / Package Dimensions

SMB



SMB mechanical data

UNIT		A	E	D	E ₁	A ₁	L	C	b
mm	max	2.44	4.70	3.94	5.59	0.20	1.5	0.305	2.2
	min	2.13	4.06	3.3	5.08	0.05	0.8	0.152	1.9
mil	max	96	185	155	220	7.9	59	12	87
	min	84	160	130	200	2.0	32	6	75

Marking

Type number	Marking code
S3AB	S3A
S3BB	S3B
S3DB	S3D
S3GB	S3G
S3JB	S3J
S3KB	S3K
S3MB	S3M

印章说明 / Marking Instructions



说明：

S3A： 为型号代码

****： 为生产批号追溯码，第1个*为年月代码，后面3个*为当月小批号代码

Note:

S3A： Product Type Code

****： Lot No. Code ,The 1st * means:YM Code ,The last 3 * means:little Lot No Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 $25 \sim 150^\circ\text{C}$ ，时间 $60 \sim 90\text{sec}$ ；
- 2、峰值温度 $245 \pm 5^\circ\text{C}$ ，时间持续为 $5 \pm 0.5\text{sec}$ ；
- 3、焊接制程冷却速度为 $2 \sim 10^\circ\text{C}/\text{sec}$ 。

Note:

- 1.Preheating: $25 \sim 150^\circ\text{C}$, Time: $60 \sim 90\text{sec}$.
- 2.Peak Temp.: $245 \pm 5^\circ\text{C}$, Duration: $5 \pm 0.5\text{sec}$.
3. Cooling Speed: $2 \sim 10^\circ\text{C}/\text{sec}$.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度： $260 \pm 5^\circ\text{C}$

时间： 10 ± 1 sec.

Temp.: $260 \pm 5^\circ\text{C}$

Time: 10 ± 1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7" × 11"	185X180X105	390X385X205

使用说明 / Notices